

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Shih-Feng Shao	05/17/2006
Ming-Yen Chiu	05/17/2006
RECEIVING PARTY DATA	
Name:	Touch Micro-System Technology INC.
Street Address:	No. 566, Gaoshih Rd., Yangmei Township
City:	Taoyuan County
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11426573
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NAME OF SUBMITTER:	WINSTON HSU
Total Attachments: 2 source=TMIP0026-0-A1-ASS#page1.tif source=TMIP0026-0-A1-ASS#page2.tif	

CH \$40.00 11426573

PATENT

Docket No TMIP0026USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Shih-Feng Shao Nationality: R.O.C.

Address: No. 33, Renzi St., Sanchung City, Taipei Hsien, Taiwan, R.O.C.

Name: Ming-Yen Chiu Nationality: R.O.C.

Address: No. 5, Lane 5, Dakian Rd., Pingdong City, Ping-Tung Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Touch Micro-System Technology INC.

Address: No. 566, Gaoshih Rd., Yangmei Township, Taoyuan County 326, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"METHOD FOR WAFER LEVEL PACKAGING AND FABRICATING CAP STRUCTURES"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

NPO#TMI-P0026-USA:0
CUST#HM0050

Assignment, Page 1 of 2

F#NPO-P0002E-US1
DSB0-095U007976

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and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this _____ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Shih-Feng Shao

Ming-Yen Chiu

Signature of INVENTOR

Shih-Feng Shao 060517

Ming-Yen Chiu 060517